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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	27MHz
Connectivity	LINbus, SPI, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	40
Program Memory Size	52KB (52K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.25K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-LQFP-64-4
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sax-xc878l-13ffa-5v-aa



XC87x Data Sheet

Revision History: V1.5 2011-03

Previous Versions: V1.4

Subjects (major changes since last revision) Page

Changes from V1.4 2010-08 to V1.5 2011-03

A new variant, SAF-XC874CM-13FVA 5V, has been added in Table 2. Page 3

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General Device Information

2.3 Pin Configuration

The pin configuration of the XC878, which is based on the PG-LQFP-64, is shown in **Figure 4**, while that of the XC874, which is based on the PG-VQFN-48 package, is shown in **Figure 5**.

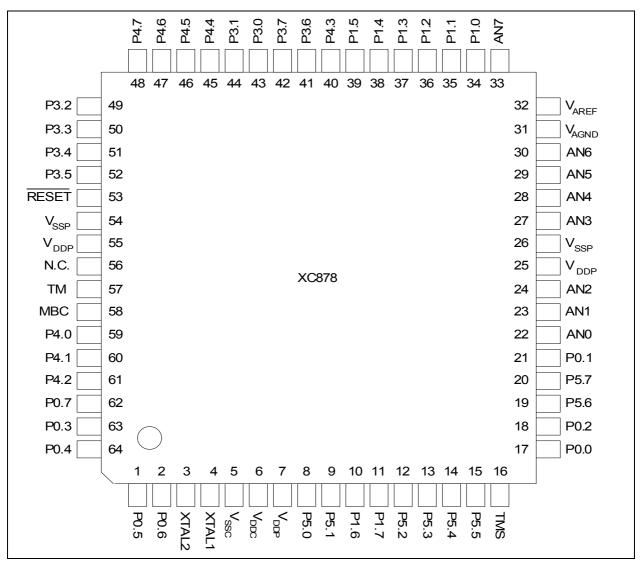


Figure 4 XC878 Pin Configuration, PG-LQFP-64 Package (top view)



General Device Information

 Table 3
 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (LQFP-64 / VQFN-48)	Туре	Reset State	Function	
P5.5	15/-		PU	CCPOS2_0 CTRAP_1 CC60_3	CCU6 Hall Input 2 CCU6 Trap Input Input of Capture/Compare channel 0
				TDO_1 TXD1_2	JTAG Serial Data Output UART1 Transmit Data Output/ Clock Output
				T2CC0_2/ EXINT3_3 A5	External Interrupt Input 3/T2CCU Capture/Compare Channel 0 Address Line 5 Output
P5.6	19/-		PU	TCK_1 RXDO1_2 T2CC1_2/ EXINT4_3 A6	JTAG Clock Input UART1 Transmit Data Output External Interrupt Input 4/T2CCU Capture/Compare Channel 1 Address Line 6 Output
P5.7	20/-		PU	TDI_1 RXD1_2 T2CC3_2/ EXINT6_4 A7	JTAG Serial Data Input UART1 Receive Data Input External Interrupt Input 6/T2CCU Capture/Compare Channel 3 Address Line 7 Output



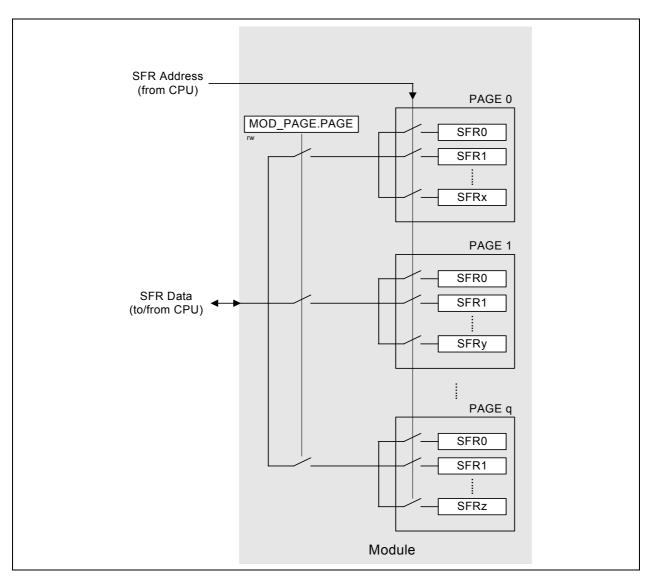


Figure 10 Address Extension by Paging

In order to access a register located in a page different from the actual one, the current page must be exited. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and the old page setting restored. This is possible with the storage fields STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

• Save the contents of PAGE in STx before overwriting with the new value (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or



3.2.4.10 CCU6 Registers

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 14 CCU6 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP =	RMAP = 0									
A3 _H	CCU6_PAGE Reset: 00H	Bit Field	С	OP STNR			0	PAGE		
	Page Register	Туре	١	N	١	V	r		rwh	
RMAP =	= 0, PAGE 0		•		•		•	•		
9A _H	CCU6_CC63SRL Reset: 00H	Bit Field				CC6	3SL			
	Capture/Compare Shadow Register for Channel CC63 Low	Туре				r	W			
9B _H	CCU6_CC63SRH Reset: 00H	Bit Field				CC6	3SH			
	Capture/Compare Shadow Register for Channel CC63 High	Туре				r	W			
9CH	CCU6_TCTR4L Reset: 00 _H Timer Control Register 4 Low	Bit Field	T12 STD	T12 STR	()	DT RES	T12 RES	T12R S	T12R R
		Туре	W	W	ı	r	W	W	W	W
9D _H	CCU6_TCTR4H Reset: 00 _H Timer Control Register 4 High	Bit Field	T13 STD	T13 STR		0		T13 RES	T13R S	T13R R
		Туре	W	W		r		W	W	W
9E _H	CCU6_MCMOUTSL Reset: 00 _H Multi-Channel Mode Output Shadow	Bit Field	STRM CM	0	MCMPS					
	Register Low	Туре	W	r	rw					
9F _H	CCU6_MCMOUTSH Reset: 00 _H Multi-Channel Mode Output Shadow	Bit Field	STRH P	0	CURHS EX			EXPHS	EXPHS	
	Register High	Туре	W	r	rw		rw			
A4 _H	CCU6_ISRL Reset: 00 _H Capture/Compare Interrupt Status	Bit Field	RT12 PM	RT12 OM	RCC6 2F	RCC6 2R	RCC6 1F	RCC6 1R	RCC6 0F	RCC6 0R
	Reset Register Low	Туре	W	W	W	W	W	W	W	W
A5 _H	CCU6_ISRH Reset: 00 _H Capture/Compare Interrupt Status	Bit Field	RSTR	RIDLE	RWH E	RCHE	0	RTRP F	RT13 PM	RT13 CM
	Reset Register High	Туре	W	W	W	W	r	W	W	w
A6 _H	CCU6_CMPMODIFL Reset: 00 _H Compare State Modification Register	Bit Field	0	MCC6 3S		0		MCC6 2S	MCC6 1S	MCC6 0S
	Low	Туре	r	W		r		W	W	W
A7 _H	CCU6_CMPMODIFH Reset: 00 _H Compare State Modification Register	Bit Field	0	MCC6 3R		0		MCC6 2R	MCC6 1R	MCC6 0R
	High	Туре	r	W	r w w					W
FA _H	CCU6_CC60SRL Reset: 00H	Bit Field				CC6	0SL			
	Capture/Compare Shadow Register for Channel CC60 Low					rv	vh			
FBH	CCU6_CC60SRH Reset: 00 _H	Bit Field				CC6	0SH			
	Capture/Compare Shadow Register for Channel CC60 High	Туре				rv	vh			



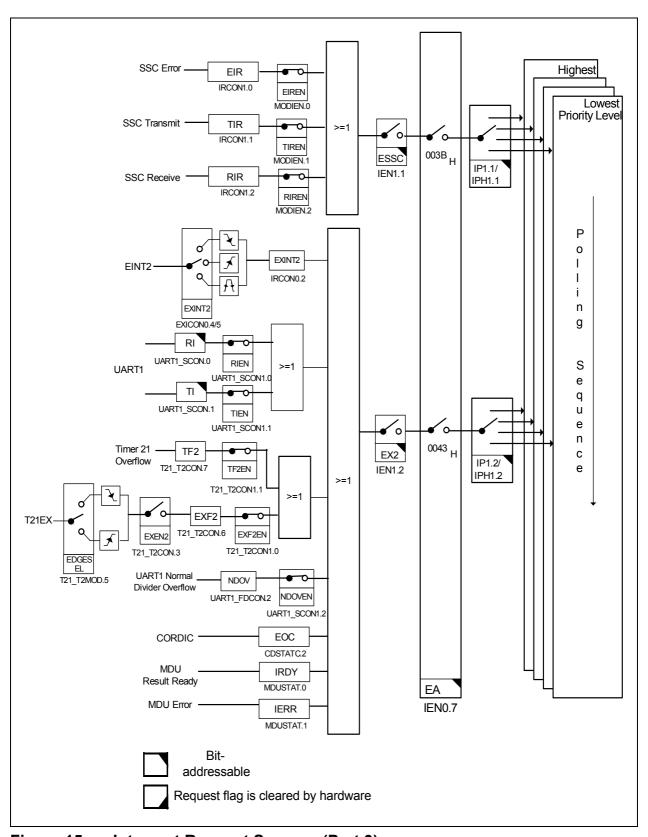


Figure 15 Interrupt Request Sources (Part 3)



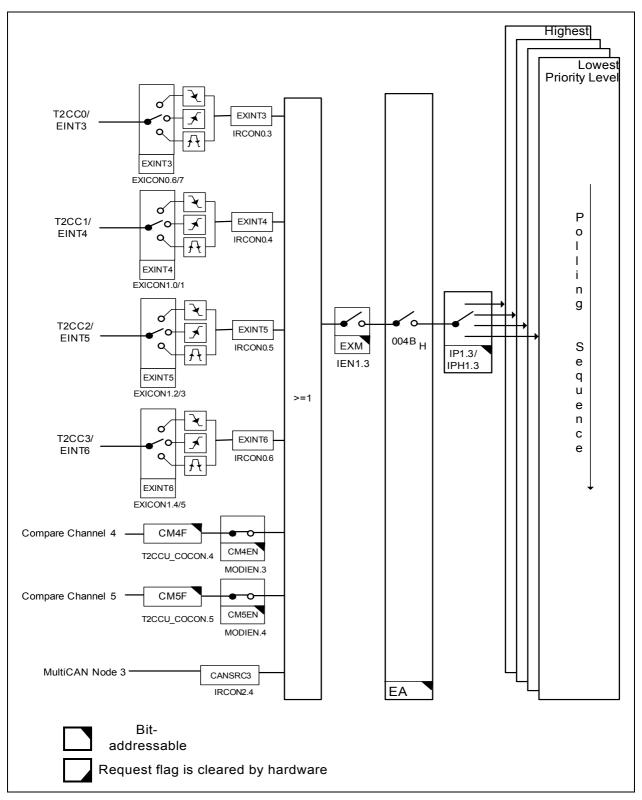


Figure 16 Interrupt Request Sources (Part 4)



Table 22 Interrupt Vector Addresses (cont'd)

Interrupt Source	Vector Address	Assignment for XC87x	Enable Bit	SFR
XINTR6	0033 _H	MultiCAN Nodes 1 and 2	EADC	IEN1
		ADC[1:0]		
XINTR7	003B _H	SSC	ESSC	
XINTR8	0043 _H	External Interrupt 2	EX2	
		T21		
		CORDIC		
		UART1		
		UART1 Fractional Divider (Normal Divider Overflow)		
		MDU[1:0]		
XINTR9 004B _H E		External Interrupt 3		
		External Interrupt 4		
		External Interrupt 5		
		External Interrupt 6		
		T2CCU		
_		MultiCAN Node 3		
XINTR10	0053 _H	CCU6 INP0	ECCIP0	
_		MultiCAN Node 4		
XINTR11	005B _H	CCU6 INP1	ECCIP1	
		MultiCAN Node 5		
XINTR12	0063 _H	CCU6 INP2	ECCIP2	
		MultiCAN Node 6		
XINTR13	006B _H	CCU6 INP3	ECCIP3	
		MultiCAN Node 7		



3.7 Reset Control

The XC87x has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC87x is first powered up, the status of certain pins (see **Table 25**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

The second type of reset in XC87x is the hardware reset. This reset function can be used during normal operation or when the chip is in power-down mode. A reset input pin RESET is provided for the hardware reset.

The Watchdog Timer (WDT) module is also capable of resetting the device if it detects a malfunction in the system.

Another type of reset that needs to be detected is a reset while the device is in power-down mode (wake-up reset). While the contents of the static RAM are undefined after a power-on reset, they are well defined after a wake-up reset from power-down mode.

3.7.1 Module Reset Behavior

Table 24 lists the functions of the XC87x and the various reset types that affect these functions. The symbol "■" signifies that the particular function is reset to its default state.

Table 24 Effect of Reset on Device Functions

Module/ Function	Wake-Up Reset	Watchdog Reset	Hardware Reset	Power-On Reset	Brownout Reset
CPU Core					
Peripherals					
On-Chip Static RAM	Not affected, Reliable	Not affected, Reliable	Not affected, Reliable	Affected, un- reliable	Affected, un- reliable
Oscillator, PLL		Not affected			
Port Pins					
EVR	The voltage regulator is switched on	Not affected	Not affected		
FLASH					
NMI	Disabled	Disabled			



resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor. **Figure 21** shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.

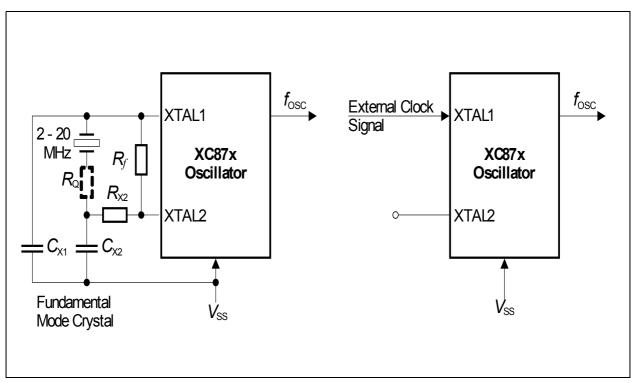


Figure 21 External Oscillator Circuitry

Note: For crystal operation, it is strongly recommended to measure the negative resistance in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the minimum and maximum values of the negative resistance specified by the crystal supplier.

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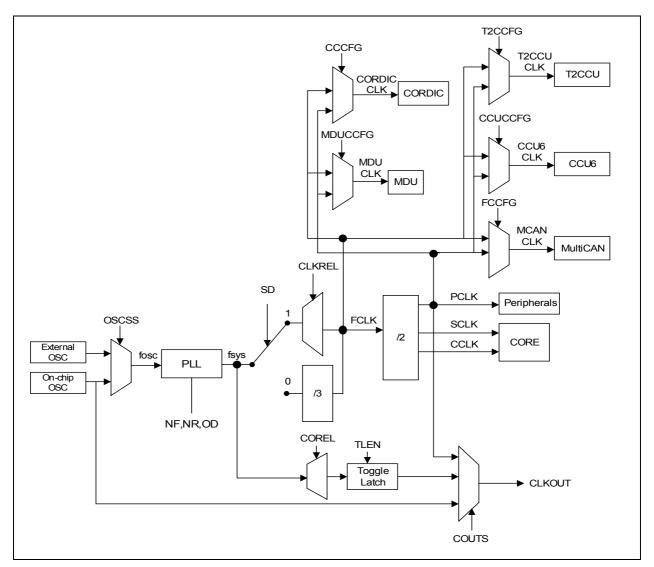


Figure 22 Clock Generation from $f_{\rm sys}$



Table 32 Deviation Error for UART with Fractional Divider enabled

$f_{ t PCLK}$	Prescaling Factor (2BRPRE)	Reload Value (BR_VALUE + 1)	STEP	Deviation Error
24 MHz	1	6 (6 _H)	59 (3B _H)	+0.03 %
12 MHz	1	3 (3 _H)	59 (3B _H)	+0.03 %
8 MHz	1	2 (2 _H)	59 (3B _H)	+0.03 %
6 MHz	1	6 (6 _H)	236 (EC _H)	+0.03 %

3.13.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3 of UART module, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

Mode 1, 3 band rate=
$$\frac{2^{\text{SMOD}} \times f_{\text{PCLK}}}{32 \times 2 \times (256 - \text{TH1})}$$

(3.6)

3.14 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see Figure 26). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV} , where n is defined by 256 - STEP.

The output frequency in normal divider mode is derived as follows:

$$f_{MOD} = f_{DIV} \times \frac{1}{256 - STEP}$$

(3.7)



3.19 Timer 2 Capture/Compare Unit

The T2CCU (Timer 2 Capture/Compare Unit) consists of the standard Timer 2 unit and a Capture/compare unit (CCU). The Capture/Compare Timer (CCT) is part of the CCU. Control is available in the T2CCU to select individually for each of its 16-bit capture/compare channel, either the Timer 2 or the Capture/Compare Timer (CCT) as the time base. Both timers have a resolution of 16 bits. The clock frequency of T2CCU, f_{T2CCU} , could be set at PCLK frequency or 2 times the PCLK frequency.

The T2CCU can be used for various digital signal generation and event capturing like pulse generation, pulse width modulation, pulse width measuring etc. Target applications include various automotive control as well as industrial (frequency generation, digital-to-analog conversion, process control etc.).

T2CCU Features

- Option to select individually for each channel, either Timer 2 or Capture/Compare Timer as time base
- Extremely flexible Capture/Compare Timer count rate by cascading with Timer 2
- Capture/Compare Timer may be 'reset' immediately by triggering overflow event
- 16-bit resolution
- Six compare channels in total
- Four capture channels multiplexed with the compare channels, in total
- Shadow register for each compare register
 - Transfer via software control or on timer overflow.
- Compare Mode 0: Compare output signal changes from the inactive level to active level on compare match. Returns to inactive level on timer overflow.
 - Active level can be defined by register bit for channel groups A and B.
 - Support of 0% to 100% duty cycle in compare mode 0.
- Compare Mode 1: Full control of the software on the compare output signal level, for the next compare match.
- Concurrent Compare Mode with channel 0
- Capture Mode 0: Capture on any external event (rising/falling/both edge) at the 4 pins T2CC0 to T2CC3.
- Capture Mode 1: Capture upon writing to the low byte of the corresponding channel capture register.
- Capture mode 0 or 1 can be established independently on the 4 capture channels.

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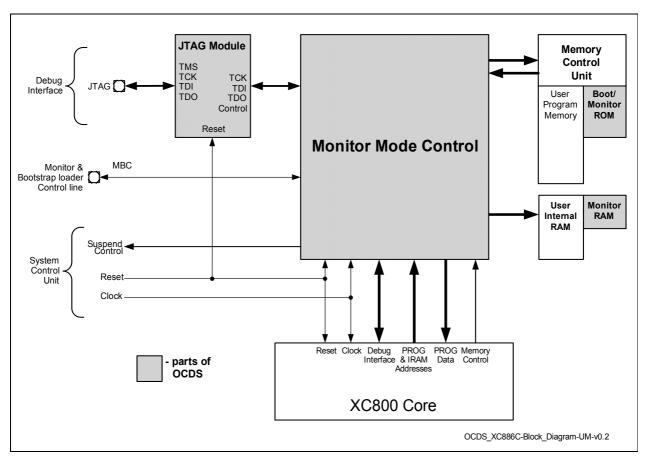


Figure 33 OCDS Block Diagram

3.23.1 JTAG ID Register

This is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode $04_{\rm H}$), and the same is also true immediately after reset.

The JTAG ID register contents for the XC87x Flash devices are given in **Table 36**.

Table 36 JTAG ID Summary

Device Type	Device Name	JTAG ID		
Flash	XC87x*-16FF	1018 2083 _H		
	XC87x*-13FF	1018 3083 _H		

Note: The asterisk (*) above denotes all possible device configurations.



4.2.4 Power Supply Current

Table 43, Table 44, Table 45 and Table 46 provide the characteristics of the power supply current in the XC87x.

Table 43 Power Supply Current Parameters (Operating Conditions apply; $V_{\text{DDP}} = 5V \text{ range}$)

Parameter	Symbol	Limit Values		Unit	Test Conditions			
		typ. ¹⁾	max. ²⁾					
V_{DDP} = 5V Range								
Active Mode	I_{DDP}	37.5	45	mA	3) SAF and SAX variants			
		40.5	48	mA	3) SAK variant			
Idle Mode	I_{DDP}	29.2	35	mA	⁴⁾ SAF and SAX variants			
		32.2	38	mA	4) SAK variant			
Active Mode with slow-	I_{DDP}	10	15	mA	5) SAF and SAX variants			
down enabled		13	18	mA	5) SAK variant			
Idle Mode with slow-	I_{DDP}	9.2	14	mA	6) SAF and SAX variants			
down enabled		12.2	17	mA	6) SAK variant			

¹⁾ The typical $I_{\rm DDP}$ values are based on preliminary measurements and are to be used as reference only. These values are periodically measured at $T_{\rm A}$ = + 25 °C and $V_{\rm DDP}$ = 5.0 V.

- 2) The maximum $I_{\rm DDP}$ values are measured under worst case conditions ($T_{\rm A}$ = + 105 °C and $V_{\rm DDP}$ = 5.5 V).
- 3) $I_{\rm DDP}$ (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz with onchip oscillator of 4 MHz, $\overline{\rm RESET} = V_{\rm DDP}$; all other pins are disconnected, no load on ports.
- 4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\text{RESET}} = V_{\text{DDP}}$; all other pins are disconnected, no load on ports.
- 5) $I_{\rm DDP}$ (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 1 MHz by setting CLKREL in CMCON to $1000_{\rm B}$, $\overline{\rm RESET} = V_{\rm DDP}$; all other pins are disconnected, no load on ports.
- 6) $I_{\rm DDP}$ (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 1 MHz by setting CLKREL in CMCON to 1000_B, RESET = $V_{\rm DDP}$; all other pins are disconnected, no load on ports.

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Table 45 Power Supply Current Parameters¹⁾ (Operating Conditions apply; $V_{\text{DDP}} = 3.3 \text{V range}$)

Parameter	Symbol	Limit	Values	Unit	Test	
	ty		max. ³⁾		Conditions	
V _{DDP} = 3.3V Range	•	_		1		
Active Mode	I_{DDP}	35.4	43	mA	4)	
Idle Mode	I_{DDP}	27.6	33	mA	5)	
Active Mode with slow-down enabled	I_{DDP}	8.6	13	mA	6)	
Idle Mode with slow-down enabled	I_{DDP}	8	12	mA	7)	

- 1) The table is only applicable to SAF and SAX variants.
- 2) The typical $I_{\rm DDP}$ values are based on preliminary measurements and are to be used as reference only. These values are periodically measured at $T_{\rm A}$ = + 25 °C and $V_{\rm DDP}$ = 3.3 V.
- 3) The maximum $I_{\rm DDP}$ values are measured under worst case conditions ($T_{\rm A}$ = + 105 °C and $V_{\rm DDP}$ = 3.6 V).
- 4) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 24 MHz with onchip oscillator of 4 MHz, $\overline{\text{RESET}} = V_{\text{DDP}}$; all other pins are disconnected, no load on ports.
- 5) $I_{\rm DDP}$ (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 24 MHz, $\overline{\rm RESET} = V_{\rm DDP}$; all other pins are disconnected, no load on ports.
- 6) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 1 MHz by setting CLKREL in CMCON to 1000_{B} , $\overline{\text{RESET}} = V_{\text{DDP}}$; all other pins are disconnected, no load on ports.
- 7) $I_{\rm DDP}$ (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 1 MHz by setting CLKREL in CMCON to 1000_B, RESET = $V_{\rm DDP}$; all other pins are disconnected, no load on ports.

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Table 46 Power Down Current¹⁾(Operating Conditions apply; $V_{\rm DDP}$ = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Conditions
		typ. ²⁾	max. ³⁾		
$V_{\rm DDP}$ = 3.3V Range					
Power-Down Mode	I_{PDP}	20	80	μА	T_{A} = + 25 °C ⁴⁾⁵⁾
		-	250	μА	T_{A} = + 85 °C ⁵⁾⁶⁾

- 1) The table is only applicable to SAF and SAX variants.
- 2) The typical $I_{\rm PDP}$ values are based on preliminary measurements and are to be used as reference only. These values are measured at $V_{\rm DDP}$ = 3.3 V.
- 3) The maximum $I_{\rm PDP}$ values are measured at $V_{\rm DDP}$ = 3.6 V.
- 4) $I_{\rm PDP}$ has a maximum value of 450 μA at $T_{\rm A}$ = + 105 $^{\circ} C$.
- 5) I_{PDP} is measured with: $\overline{\text{RESET}} = V_{\text{DDP}}$, $V_{\text{AGND}} = V_{\text{SS}}$, RXD/INT0 = V_{DDP} ; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.
- 6) Not subjected to production test, verified by design/characterization.

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4.3.4 On-Chip Oscillator Characteristics

Table 49 provides the characteristics of the on-chip oscillator in the XC87x.

 Table 49
 On-chip Oscillator Characteristics (Operating Conditions apply)

Parameter	Symbol		Lin	Limit Values			Test Conditions
			min.	typ.	max.		
Nominal frequency	f_{NOM}	CC	3.88	4	4.12	MHz	under nominal conditions ¹⁾ after IFX-backend trimming
Long term frequency deviation	Δf_{LT}	CC	-5	_	5	%	with respect to $f_{\rm NOM}$, over lifetime and temperature (-40°C to 105°C), for one given device after trimming
Short term frequency deviation	Δf_{ST}	CC	-1.0	_	1.0	%	within one LIN message (<10 ms 100 ms)

¹⁾ Nominal condition: $V_{\rm DDC}$ = 2.5 V, $T_{\rm A}$ = + 25°C.



4.3.7 JTAG Timing

Table 53 provides the characteristics of the JTAG timing in the XC87x.

Table 53 TCK Clock Timing (Operating Conditions apply; CL = 50 pF)

Parameter	Sym	Symbol		Limits		Test Conditions
			min	max		
TCK clock period	t_{TCK}	SR	50	-	ns	1)
TCK high time	<i>t</i> ₁	SR	20	-	ns	1)
TCK low time	t_2	SR	20	-	ns	1)
TCK clock rise time	t_3	SR	-	4	ns	1)
TCK clock fall time	t_4	SR	-	4	ns	1)

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

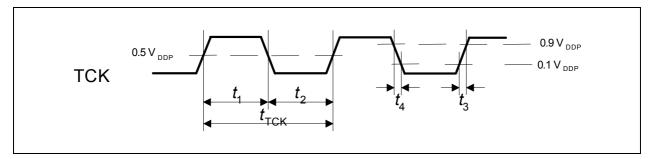


Figure 44 TCK Clock Timing

Table 54 JTAG Timing (Operating Conditions apply; CL = 50 pF)

Parameter	Symbol		Limits		Unit	Test Conditions
			min	max		
TMS setup to TCK _√	t_1	SR	8	-	ns	1)
TMS hold to TCK _√	t_2	SR	0	-	ns	1)
TDI setup to TCK	t_1	SR	8	-	ns	1)
TDI hold to TCK √	t_2	SR	4	-	ns	1)
TDO valid output from TCK	t_3	CC	-	24	ns	5V Device ¹⁾
			-	31	ns	3.3V Device ¹⁾